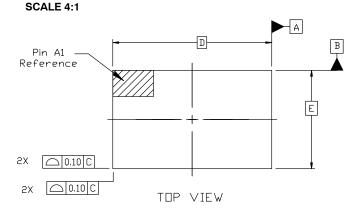
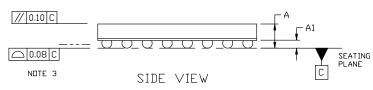
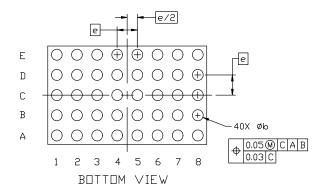




**DATE 20 DEC 2022** 



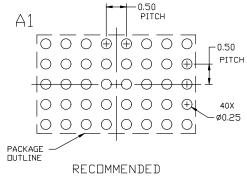




## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

	MILLIMETERS	
DIM	MIN.	MAX.
Α		0.65
A1	0.14	0.24
b	0.22	0.32
D	3.94	BSC
E	2.44	BSC
е	0.50	BSC



## MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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DESCRIPTION:	WLCSP40, 2.44X3.94		PAGE 1 OF 1

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